

**PATENT** 



## IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

**Applicants** 

Wilkins

Title

Die-First Multi-Chip Modules And Methods Of

Manufacture

Application No.

10/724,981

Filed

November 30, 2003

Attorney Docket No.

783403605015

I hereby certify that this correspondence is being deposited today with the United States Postal Service as first class mail in an envelope addressed to: Commissioner for

Patents, P.O. Box 1450, Alexandria, VA

**STATUS INQUIRY** 

m August 29.

Commissioner for Patents P.O. Box 1450 Alexandria, VA 22313-1450

Dear Sir:

The above-referenced application was filed in the United States on November 30, 2003, and we have not yet received an Office Action or Notice of Allowance for the same. Please advise the undersigned when we should expect to receive an action or notice.

Respectfully submitted,

Paul E. Franz

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Date: 8/29/5